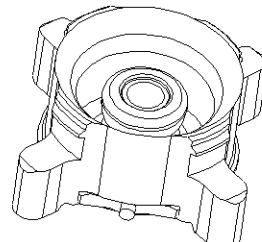
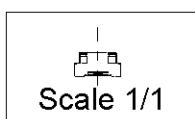
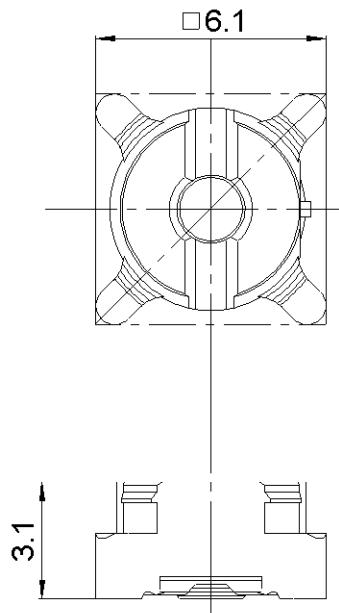


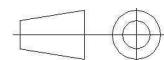
SMTJACK RECEPTACLE

R223.424.000

Series : MMBX



All dimensions are in mm.

PLATING (μm)

COMPONENTS	MATERIALS	PLATING (μm)
BODY	BRASS	NPGR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT	-	-
INSULATOR	LIQUID CRYSTAL POLYMER	-
GASKET	-	-
OTHERS PARTS	-	-

Issue : 0736 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMTJACK RECEPTACLE

R223.424.000

Series : MMBX

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATIONELECTRICAL CHARACTERISTICS

Impedance	50 Ω
Frequency	0-12.4 GHz
VSWR	1.065 + 0,0000 x F(GHz) Maxi
Insertion loss	0.12 $\sqrt{F(\text{GHz})}$ dB Maxi
RF leakage	- (100 - F(GHz)) dB Maxi
Voltage rating	330 Veff Maxi
Dielectric withstanding voltage	1000 Veff mini
Insulation resistance	1000 M Ω mini

ENVIRONMENTAL

Operating temperature	-55/+155 °C
Hermetic seal	NA Atm.cm ³ /s
Panel leakage	NA

OTHER CHARACTERISTICSAssembly instruction **NA**

Others :
 to 6 GHz
 Interface MMBX only, up to 2.5 GHz
 PCB to PCB -45dB up to 2.5 GHz

Mated pair height 6.7mm

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	10 N mini
Axial force – Opposite end	10 N mini
Torque	NA N.cm mini

Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm

Mating life	100 Cycles mini
Weight	0,3050 g

Issue : 0736 B

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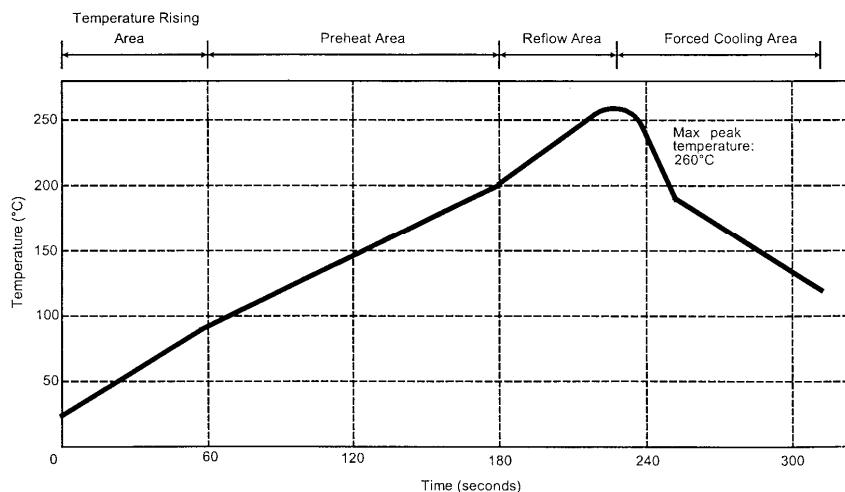
SMTJACK RECEPTACLE**R223.424.000**

Series : MMBX

SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
A video camera is recommended for positioning of the component.
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0736 B

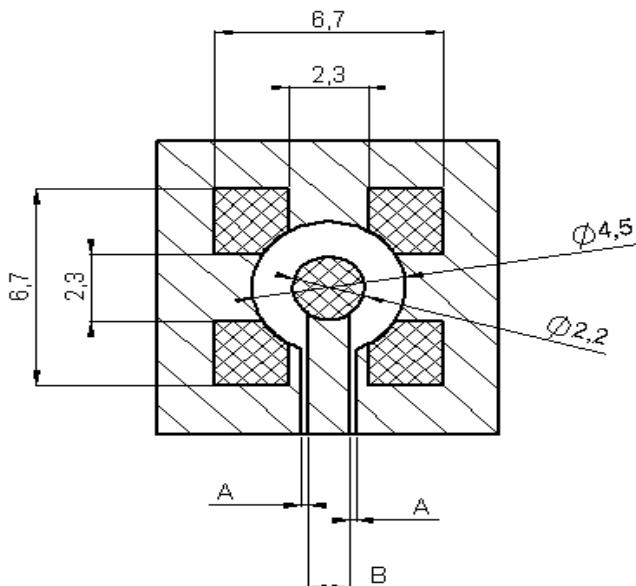
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SMTJACK RECEPTACLE

R223.424.000

Series : MMBX

MMBX SERIES INFORMATIONS**PCB****COPLANAR LINE**

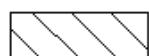
Pattern and signal are on the same side

The material of PCB is epoxy resin (FR4).

(Er = 4.6)

The solder resist should be printed

Except for the land pattern on the PCB

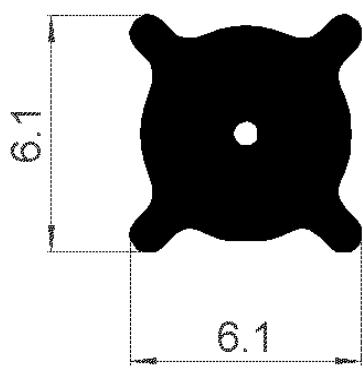
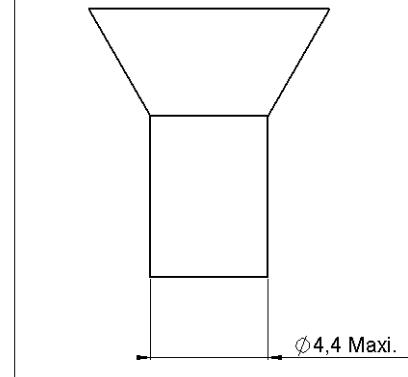
 Pattern

 Land for solder paste
APPLICATION 75Ω**WITH B = 0,55mm**

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

APPLICATION 50Ω**WITH B = 1,2mm**

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1,6	0,210

SHADOW FOR VIDEO CAMERA**ASPIRATION PORT**

Issue : 0736 B

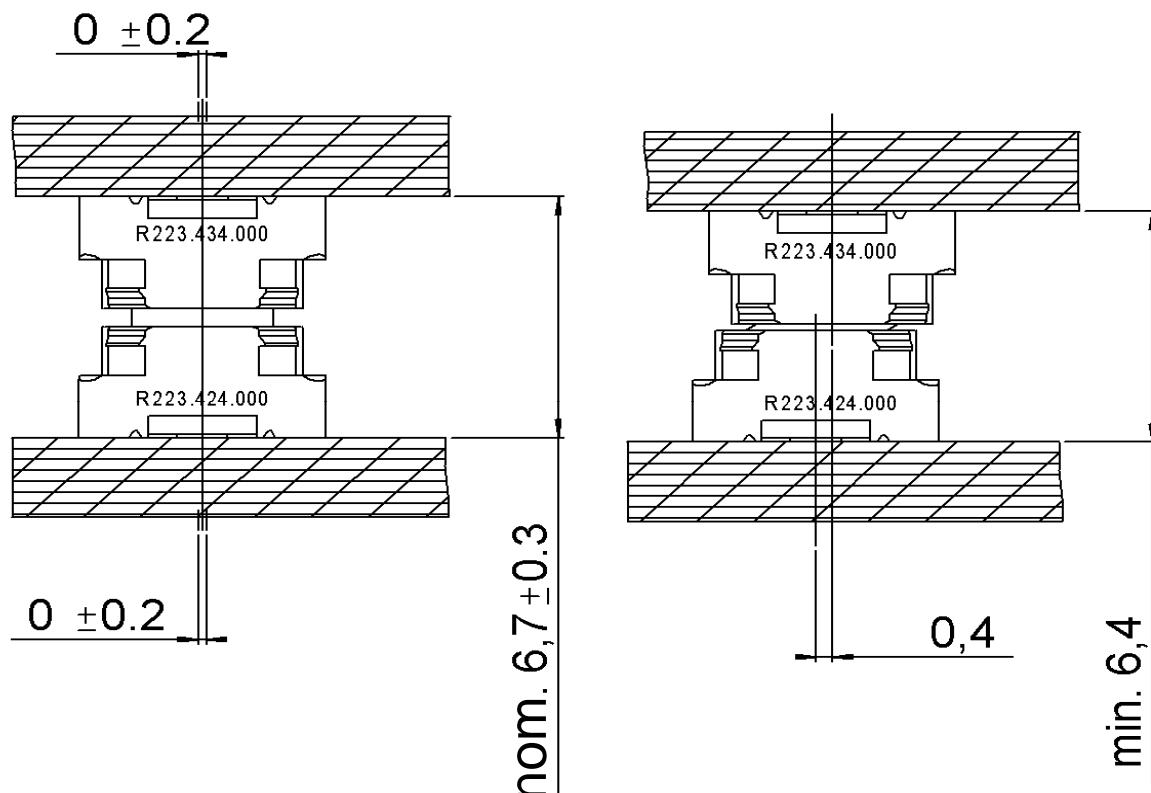
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SMTJACK RECEPTACLE

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Series : MMBX

MMBX SERIES INFORMATIONS

**Issue : 0736 B**

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